

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

1-12 (Cancelled).

13. (Currently Amended) A plasma processing apparatus that performs plasma processing on a workpiece placed on an electrode provided inside a processing chamber, comprising:

an electrically conductive ring body encompassing the periphery of said workpiece placed on said electrode;

an electrically insulating ring body encompassing the periphery of said electrically conductive ring body;

a thermal conductivity adjusting member, for adjusting a thermal conductivity between the electrode and the electrically conductive ring body, provided between said electrode and said electrically conductive ring body.

14. (Currently Amended) A plasma processing apparatus according to claim 13, further comprising a means for heat application provided at said electrically insulating ring body.

15. (Currently Amended) A plasma processing apparatus according to claim 13, wherein [[a]] said thermal conductivity between said workpiece and said electrode is represented as Q,

wherein an area of a surface of said electrically conductive ring body contacting said plasma is represented as S1,

wherein an area of a surface of said electrically conductive ring body contacting said electrode is represented as S2, and

wherein said thermal conductivity adjusting member achieves a thermal conductivity R express as  $R = Q \times S1/S2$ .

16. (Previously Presented) A plasma processing apparatus according to claim 13, further comprising a means for pressure application that applies a pressure to said electrically conductive ring body toward said electrode and is capable of adjusting the level of pressure applied to said electrically conductive ring body.